

AM26C31 Quadruple Differential Line Driver

1 Features

- Meets or exceeds the requirements of TIA/EIA-422-B and ITU recommendation V.11
- Low power, $I_{CC} = 100\mu\text{A}$ typical
- Operates from a single 5V supply
- High speed, $t_{PLH} = t_{PHL} = 7\text{ns}$ typical
- Low pulse distortion, $t_{sk(p)} = 0.5\text{ns}$ typical
- High output impedance in power-off conditions
- Improved replacement for AM26LS31 device
- Available in Q-temp automotive
 - High-reliability automotive applications
 - Configuration control and print support
 - Qualification to automotive standards
- On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

2 Applications

- Chemical and gas sensors
- Field transmitters: temperature sensors and pressure sensors
- Military: radars and sonars
- Motor control: brushless DC and brushed DC
- Military and avionics imaging
- Temperature sensors and controllers using modbus

3 Description

The AM26C31 device is a differential line driver with complementary outputs, designed to meet the requirements of TIA/EIA-422-B and ITU (formerly CCITT). The 3-state outputs have high-current capability for driving balanced lines, such as twisted-pair or parallel-wire transmission lines, and they provide the high-impedance state in the power-off condition. The enable functions are common to all four drivers and offer the choice of an active-high (G) or active-low (\bar{G}) enable input. BiCMOS circuitry reduces power consumption without sacrificing speed.

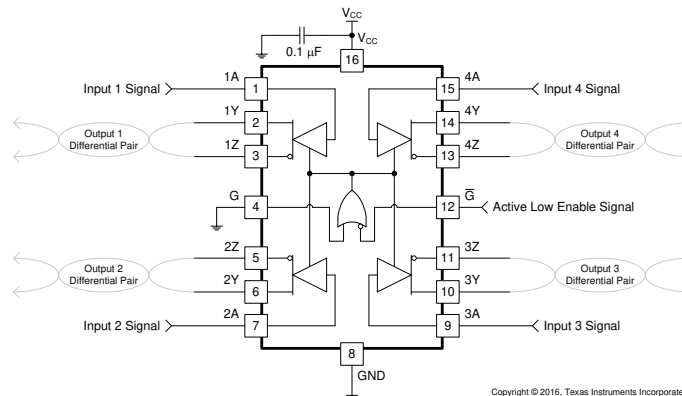
The AM26C31C device is characterized for operation from 0°C to 70°C , the AM26C31I device is characterized for operation from -40°C to $+85^{\circ}\text{C}$, the AM26C31Q device is characterized for operation over the automotive temperature range of -40°C to $+125^{\circ}\text{C}$, and the AM26C31M device is characterized for operation over the full military temperature range of -55°C to $+125^{\circ}\text{C}$.

Package Information

| PART NUMBER | PACKAGE ⁽¹⁾ | PACKAGE SIZE ⁽²⁾ |
|-------------|------------------------|-----------------------------|
| AM26C31 | CDIP (J, 16) | 19.56mm × 6.92mm |
| | PDIP (N, 16) | 19.3mm × 6.35mm |
| | SO (NS, 16) | 10.3mm × 5.3mm |
| | CFP (W, 16) | 10.3mm × 6.73mm |
| | SOIC (D, 16) | 9.9mm × 3.91mm |
| | SSOP (DB, 16) | 6.2mm × 5.3mm |
| | TSSOP (PW, 16) | 5.0mm × 4.4mm |
| | LCCC (FK, 20) | 8.89mm × 8.89mm |

(1) For more information, see [Section 11](#).

(2) The package size (length × width) is a nominal value and includes pins, where applicable.



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Common Application Diagram



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4 Pin Configuration and Functions

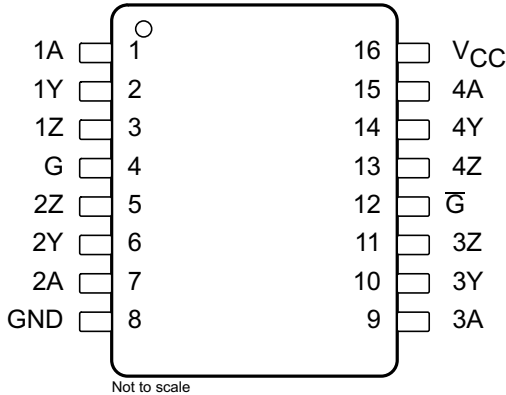


Figure 4-1. J (CDIP), W (CFP), D (SOIC), DB (SSOP), NS (SO), N (PDIP), or PW (TSSOP) Package 16-Pin (Top View)

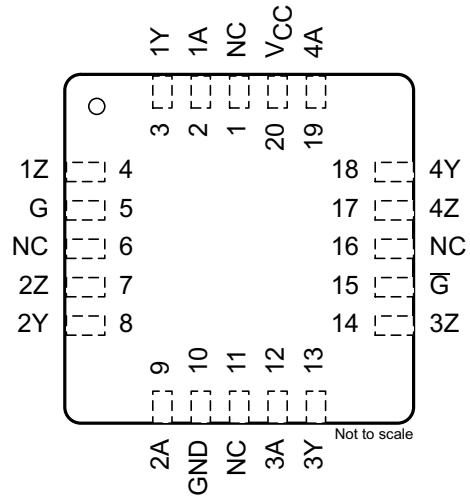


Figure 4-2. FK (LCCC) Package, 20-Pin (Top View)

Table 4-1. Pin Functions

| NAME | PIN | | TYPE | DESCRIPTION |
|-------------------|--|--------------|------|--------------------------|
| | CDIP, CFP, SOIC, SSOP, SO, PDIP, TSSOP | LCCC | | |
| 1A | 1 | 2 | I | Driver 1 input |
| 1Y | 2 | 3 | O | Driver 1 output |
| 1Z | 3 | 4 | O | Driver 1 inverted output |
| 2A | 7 | 9 | I | Driver 2 input |
| 2Y | 6 | 8 | O | Driver 2 output |
| 2Z | 5 | 7 | O | Driver 2 inverted output |
| 3A | 9 | 12 | I | Driver 3 input |
| 3Y | 10 | 13 | O | Driver 3 output |
| 3Z | 11 | 14 | O | Driver 3 inverted output |
| 4A | 15 | 19 | I | Driver 3 input |
| 4Y | 14 | 18 | O | Driver 3 output |
| 4Z | 13 | 17 | O | Driver 3 inverted output |
| G | 4 | 5 | I | Active high enable |
| Ḡ | 12 | 15 | I | Active low enable |
| GND | 8 | 10 | — | Ground pin |
| NC ⁽¹⁾ | — | 1, 6, 11, 16 | — | No internal connection |
| V _{CC} | 16 | 20 | — | Power pin |

(1) NC – No connection

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

| | | MIN | MAX | UNIT |
|------------------------------------|--|------|-----------------------|------|
| V _{CC} | Supply voltage ⁽²⁾ | -0.5 | 7 | V |
| V _I | Input voltage | -0.5 | V _{CC} + 0.5 | V |
| V _{ID} | Differential input voltage | -14 | 14 | V |
| V _O | Output voltage | -0.5 | 7 | V |
| I _{IK} I _{OK} | Input or output clamp current | | ±20 | mA |
| I _O | Output current | | ±150 | mA |
| | V _{CC} current | | 200 | mA |
| | GND current | -200 | | mA |
| T _J | Operating virtual junction temperature | | 150 | °C |
| T _{stg} | Storage temperature | -65 | 150 | °C |

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values, except differential voltages, are with respect to the network ground terminal.

5.2 ESD Ratings

| | | | VALUE | UNIT |
|--------------------|-------------------------|--|-------|------|
| V _(ESD) | Electrostatic discharge | Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾ | ±2000 | V |
| | | Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾ | ±1000 | |

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

| | | | MIN | NOM | MAX | UNIT |
|-----------------|--------------------------------|----------|-----|-----|-----|------|
| V _{CC} | Supply voltage | | 4.5 | 5 | 5.5 | V |
| V _{ID} | Differential input voltage | | | ±7 | | V |
| V _{IH} | High-level input voltage | | 2 | | | V |
| V _{IL} | Low-level input voltage | | | | 0.8 | V |
| I _{OH} | High-level output current | | | | -20 | mA |
| I _{OL} | Low-level output current | | | | 20 | mA |
| T _A | Operating free-air temperature | AM26C31C | 0 | | 70 | °C |
| | | AM26C31I | -40 | | 85 | |
| | | AM26C31Q | -40 | | 125 | |
| | | AM26C31M | -55 | | 125 | |

5.4 Thermal Information

| THERMAL METRIC ⁽¹⁾ | AM26C31 | | | | | | | | | UNIT |
|-------------------------------|---|-----------|------------|---------|----------|----------|---------------------|----------------------|---------------------|------|
| | D (SOIC) | DB (SSOP) | PW (TSSOP) | NS (SO) | N (PDIP) | J (CDIP) | W (CFP) | FK (LCCC) | | |
| | 16 PINS | 16 PINS | 16 PINS | 16 PINS | 16 PINS | 16 PINS | 16 PINS | 16 PINS | 16 PINS | |
| R _{θJA} | Junction-to-ambient thermal resistance ^{(2) (3)} | 84.6 | 102.6 | 107.5 | 88.5 | 60.6 | — | — | — | °C/W |
| R _{θJC(top)} | Junction-to-case (top) thermal resistance | 43.5 | 48.7 | 38.4 | 46.2 | 48.1 | 39.3 ⁽⁴⁾ | 58.9 ⁽⁴⁾ | 37.1 ⁽⁴⁾ | °C/W |
| R _{θJB} | Junction-to-board thermal resistance | 43.2 | 54.3 | 53.7 | 50.7 | 40.6 | 56.4 ⁽⁴⁾ | 109.3 ⁽⁴⁾ | 36.2 ⁽⁴⁾ | °C/W |
| ψ _{JT} | Junction-to-top characterization parameter | 10.4 | 11.8 | 3.2 | 13.5 | 27.5 | — | — | — | °C/W |
| ψ _{JB} | Junction-to-board characterization parameter | 42.8 | 53.5 | 53.1 | 50.3 | 40.3 | — | — | — | °C/W |
| R _{θJC(bot)} | Junction-to-case (bottom) thermal resistance | n/a | n/a | n/a | n/a | n/a | 12 ⁽⁴⁾ | 5.7 ⁽⁴⁾ | 4.3 ⁽⁴⁾ | °C/W |

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.
- (2) Maximum power dissipation is a function of T_{J(max)}, R_{θJA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is P_D = (T_{J(max)} – T_A) / R_{θJA}. Operating at the absolute maximum T_J of 150°C can affect reliability.
- (3) The package thermal impedance is calculated in accordance with JESD 51-7.
- (4) Modelling assumption: MIL-STD-883 for R_{θJC(top)} and R_{θJC(bot)} JESD51 for R_{θJB}.

5.5 Electrical Characteristics: AM26C31C and AM26C31I

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | | MIN | TYP ⁽¹⁾ | MAX | UNIT |
|---------------------|---|---|--|-----|--------------------|------|------|
| V _{OH} | High-level output voltage | I _O = –20mA | | 2.4 | 3.4 | | V |
| V _{OL} | Low-level output voltage | I _O = 20mA | | | 0.2 | 0.4 | V |
| V _{OD} | Differential output voltage magnitude | R _L = 100Ω, see Figure 6-1 | | 2 | 3.1 | | V |
| Δ V _{OD} | Change in magnitude of differential output voltage ⁽²⁾ | R _L = 100Ω, see Figure 6-1 | | | | ±0.4 | V |
| V _{OC} | Common-mode output voltage | R _L = 100Ω, see Figure 6-1 | | | | 3 | V |
| Δ V _{OC} | Change in magnitude of common-mode output voltage ⁽²⁾ | R _L = 100Ω, see Figure 6-1 | | | | ±0.4 | V |
| I _I | Input current | V _I = V _{CC} or GND | | | | ±1 | μA |
| I _{O(off)} | Driver output current with power off | V _{CC} = 0 | V _O = 6V | | | 100 | μA |
| | | | V _O = –0.25V | | | –100 | |
| I _{OS} | Driver output short-circuit current | V _O = 0 | | –30 | | –150 | mA |
| I _{OZ} | High-impedance off-state output current | V _O = 2.5V | | | | 20 | μA |
| | | V _O = 0.5V | | | | –20 | |
| I _{CC} | Quiescent supply current | I _O = 0 | V _I = 0 or 5V | | | 100 | μA |
| | | | V _I = 2.4V or 0.5V ⁽³⁾ | | | 1.5 | |
| C _i | Input capacitance | | | | | 6 | pF |

- (1) All typical values are at V_{CC} = 5V and T_A = 25°C.
- (2) Δ|V_{OD}| and Δ|V_{OC}| are the changes in magnitude of V_{OD} and V_{OC}, respectively, that occur when the input is changed from a high level to a low level.
- (3) This parameter is measured per input. All other inputs are at 0V or 5V.

5.6 Electrical Characteristics: AM26C31Q and AM26C31M

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | MIN | TYP ⁽¹⁾ | MAX | UNIT |
|---------------------|---|---|--|--------------------|------|------|
| V _{OH} | High-level output voltage | I _O = -20mA | 2.2 | 3.4 | | V |
| V _{OL} | Low-level output voltage | I _O = 20mA | | 0.2 | 0.4 | V |
| V _{OD} | Differential output voltage magnitude | R _L = 100Ω, see Figure 6-1 | 2 | 3.1 | | V |
| Δ V _{OD} | Change in magnitude of differential output voltage ⁽²⁾ | R _L = 100Ω, see Figure 6-1 | | | ±0.4 | V |
| V _{OC} | Common-mode output voltage | R _L = 100Ω, see Figure 6-1 | | | 3 | V |
| Δ V _{OC} | Change in magnitude of common-mode output voltage ⁽²⁾ | R _L = 100Ω, see Figure 6-1 | | | ±0.4 | V |
| I _I | Input current | V _I = V _{CC} or GND | | | ±1 | μA |
| I _{O(off)} | Driver output current with power off | V _{CC} = 0 | V _O = 6V | | 100 | μA |
| | | | V _O = -0.25V | | -100 | |
| I _{OS} | Driver output short-circuit current | V _O = 0 | | | -170 | mA |
| I _{OZ} | High-impedance off-state output current | V _O = 2.5V | | | 20 | μA |
| | | V _O = 0.5V | | | -20 | |
| I _{CC} | Quiescent supply current | I _O = 0 | V _I = 0 or 5V | | 100 | μA |
| | | | V _I = 2.4V or 0.5V ⁽³⁾ | | 3.2 | |
| C _i | Input capacitance | | | 6 | | pF |

(1) All typical values are at V_{CC} = 5V and T_A = 25°C.

(2) Δ|V_{OD}| and Δ|V_{OC}| are the changes in magnitude of V_{OD} and V_{OC}, respectively, that occur when the input is changed from a high level to a low level.

(3) This parameter is measured per input. All other inputs are at 0V or 5V.

5.7 Switching Characteristics: AM26C31C and AM26C31I

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | MIN | TYP ⁽¹⁾ | MAX | UNIT |
|---|--|------------------------------|-----|--------------------|-----|------|
| t _{PLH} | Propagation delay time, low-to-high-level output | S1 is open, see Figure 6-2 | 3 | 7 | 12 | ns |
| t _{PHL} | Propagation delay time, high-to-low-level output | | 3 | 7 | 12 | |
| t _{sk(p)} | Pulse skew time (t _{PLH} - t _{PHL}) | S1 is open, see Figure 6-2 | | 0.5 | 4 | ns |
| t _{r(OD)} , t _{f(OD)} | Differential output rise and fall times | S1 is open, see Figure 6-3 | | 5 | 10 | ns |
| t _{PZH} | Output enable time to high level | S1 is closed, see Figure 6-4 | | 10 | 19 | ns |
| t _{PZL} | Output enable time to low level | | 10 | 19 | | |
| t _{PHZ} | Output disable time from high level | S1 is closed, see Figure 6-4 | | 7 | 16 | ns |
| t _{PLZ} | Output disable time from low level | | 7 | 16 | | |
| C _{pd} | Power dissipation capacitance (each driver) ⁽²⁾ | S1 is open, see Figure 6-2 | | 170 | | pF |

(1) All typical values are at V_{CC} = 5V and T_A = 25°C.

(2) C_{pd} is used to estimate the switching losses according to P_D = C_{pd} × V_{CC}² × f, where f is the switching frequency.

5.8 Switching Characteristics: AM26C31Q and AM26C31M

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | MIN | TYP ⁽¹⁾ | MAX | UNIT |
|---|--|--|-----|--------------------|-----|------|
| t _{PLH} | Propagation delay time, low-to-high-level output | S1 is open, see Figure 6-2 | | 7 | 12 | ns |
| t _{PHL} | Propagation delay time, high-to-low-level output | | | 6.5 | 12 | |
| t _{sk(p)} | Pulse skew time (t _{PLH} – t _{PHL}) | S1 is open, see Figure 6-2 | | 0.5 | 4 | ns |
| t _{r(OD)} , t _{f(OD)} | Differential output rise and fall times | S1 is open, see Figure 6-3 | | 5 | 12 | ns |
| t _{PZH} | Output enable time to high level | S1 is closed, see Figure 6-4 | | 10 | 19 | ns |
| t _{PZL} | Output enable time to low level | | | 10 | 19 | |
| t _{PHZ} | Output disable time from high level | S1 is closed, see Figure 6-4 | | 7 | 16 | ns |
| t _{PLZ} | Output disable time from low level | | | 7 | 16 | |
| C _{pd} | Power dissipation capacitance (each driver) ⁽²⁾ | S1 is open, see Figure 6-2 | | 100 | | pF |

(1) All typical values are at V_{CC} = 5V and T_A = 25°C.

(2) C_{pd} is used to estimate the switching losses according to P_D = C_{pd} × V_{CC}² × f, where f is the switching frequency.

5.9 Typical Characteristics

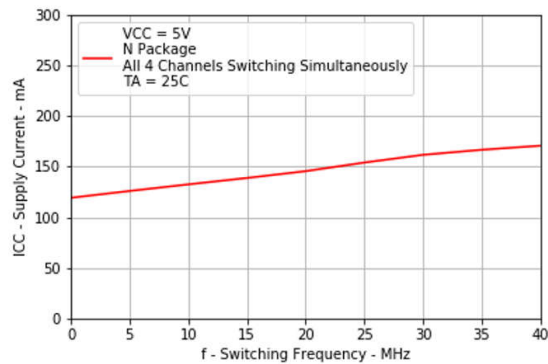


Figure 5-1. Supply Current vs Switching Frequency

6 Parameter Measurement Information

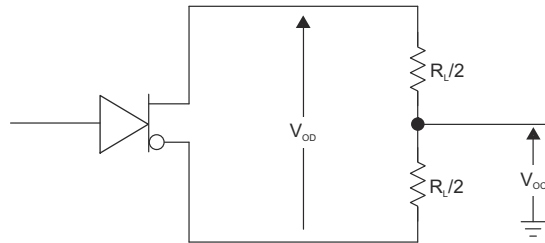
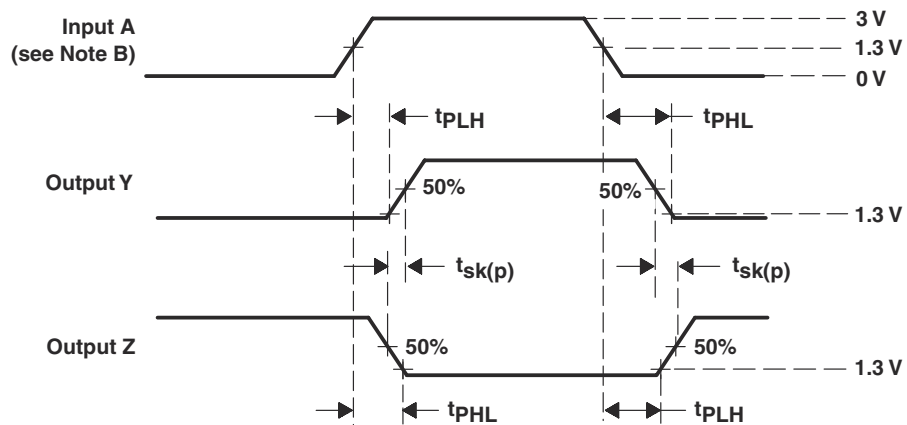
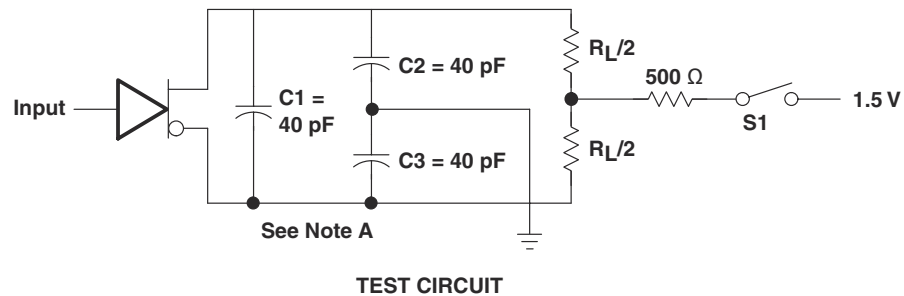
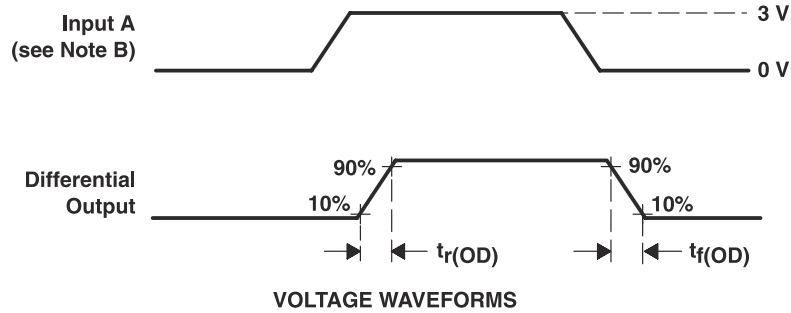
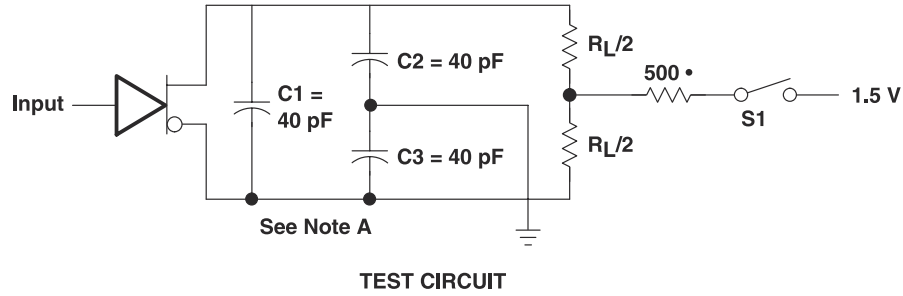


Figure 6-1. Differential and Common-Mode Output Voltages



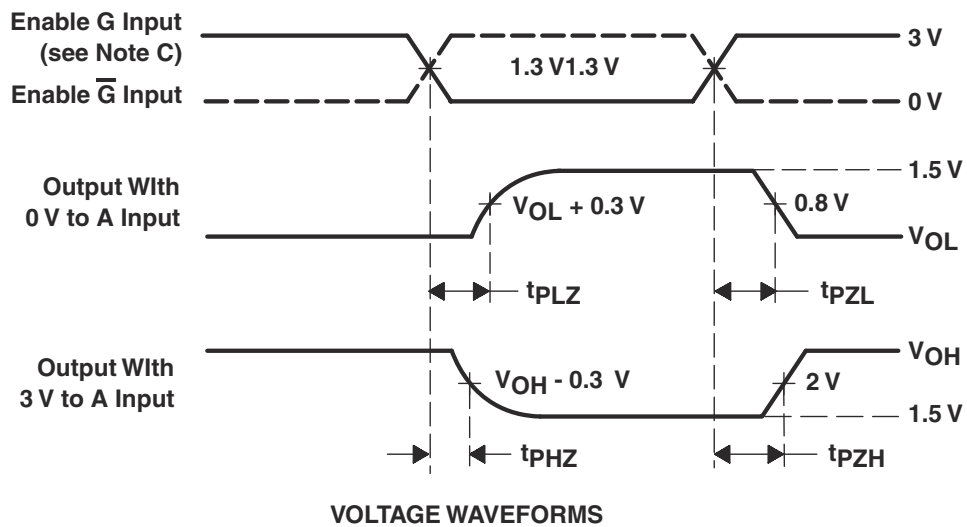
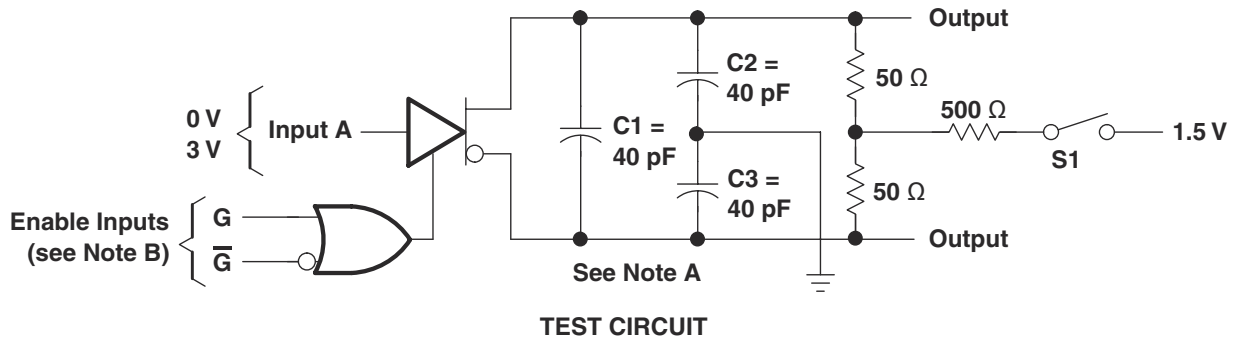
- A. C1, C2, and C3 include probe and jig capacitance.
- B. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1\text{MHz}$, duty cycle $\leq 50\%$, and $t_r, t_f \leq 6\text{ns}$.

Figure 6-2. Propagation Delay Time and Skew Waveforms and Test Circuit



- A. C1, C2, and C3 include probe and jig capacitance.
- B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1MHz, duty cycle ≤ 50%, and $t_r, t_f \leq 6\text{ns}$.

Figure 6-3. Differential-Output Rise and Fall-Time Waveforms and Test Circuit



- A. C1, C2, and C3 include probe and jig capacitance.
- B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1MHz, duty cycle ≤ 50%, and $t_r, t_f \leq 6\text{ns}$.
- C. Each enable is tested separately.

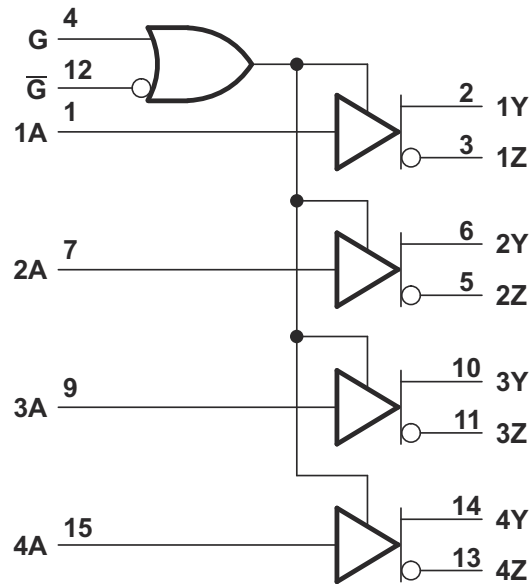
Figure 6-4. Output Enable and Disable Time Waveforms and Test Circuit

7 Detailed Description

7.1 Overview

The AM26C31 is a quadruple differential line driver with complementary outputs. The device is designed to meet the requirements of TIA/EIA-422-B and ITU (formerly CCITT), and it is generally used to communicate over relatively long wires in noisy environments.

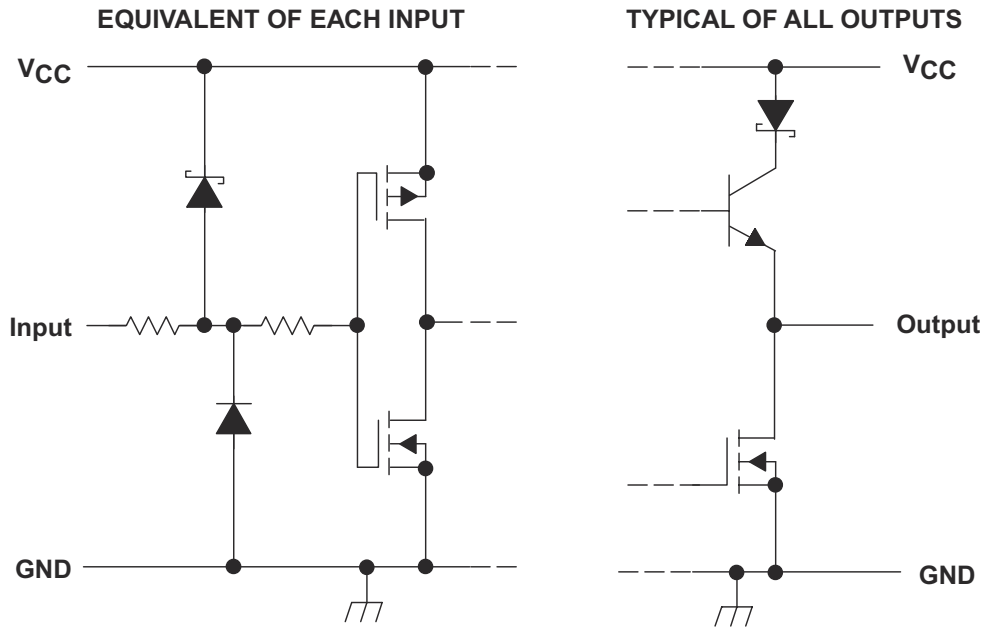
7.2 Functional Block Diagrams



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Pin numbers shown are for the D, DB, J, N, NS, PW, and W packages.

Figure 7-1. Logic Diagram (Positive Logic)



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Figure 7-2. Schematics of Inputs and Outputs

7.3 Feature Description

7.3.1 Active-High and Active-Low

The device can be configured using the G and \bar{G} logic inputs to select transmitter output. A logic high on the G pin or a logic low on the \bar{G} pin enables the device to operate. These pins are simply a way to configure the logic to match that of the receiving or transmitting controller or microprocessor.

7.3.2 Operates From a Single 5V Supply

Both the logic and transmitters operate from a single 5V rail, making designs much more simple. The line drivers and receivers can operate off the same rail as the host controller or a similar low voltage supply, thus simplifying power structure.

7.4 Device Functional Modes

Table 7-1 lists the functional modes of the AM26C31.

Table 7-1. Function Table (Each Driver)⁽¹⁾

| INPUT A | ENABLES | | OUTPUTS | |
|------------|---------|-----------|---------|---|
| | G | \bar{G} | Y | Z |
| H | H | X | H | L |
| L | H | X | L | H |
| H | X | L | H | L |
| L | X | L | L | H |
| X | L | H | Z | Z |

- (1) H = High level,
L = Low level,
X = Irrelevant,
Z = High impedance (off)

8 Application Information Disclaimer

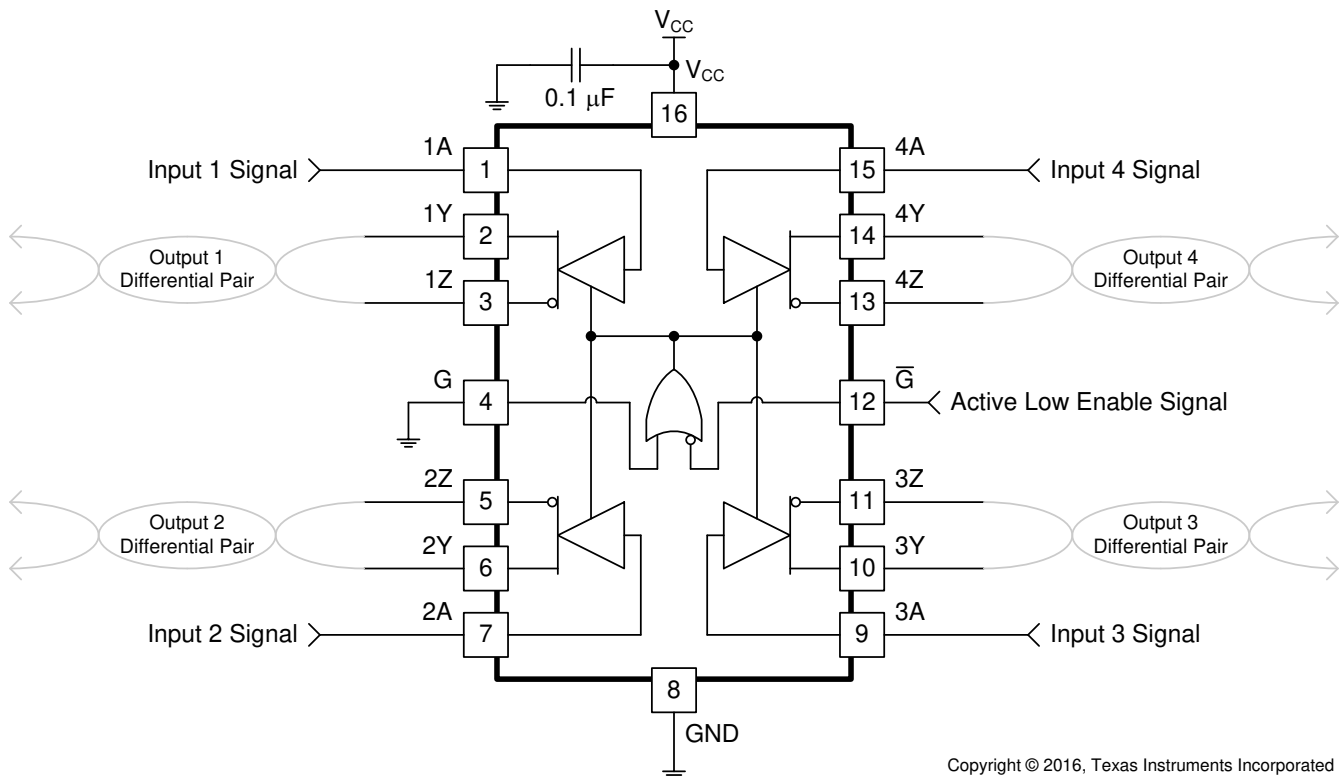
Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

8.1 Application Information

When designing a system that uses drivers, receivers, and transceivers that comply with RS-422, proper cable termination is essential for highly reliable applications with reduced reflections in the transmission line. Because RS-422 allows only one driver on the bus, if termination is used, it is placed only at the end of the cable near the last receiver. Factors to consider when determining the type of termination usually are performance requirements of the application and the ever-present factor, cost. The different types of termination techniques discussed are unterminated lines, parallel termination, AC termination, and multipoint termination. For laboratory experiments, 100 feet of 100Ω, 24-AWG, twisted-pair cable (Bertek) was used. A single driver and receiver, TI AM26C31C and AM26C32C, respectively, were tested at room temperature with a 5V supply voltage. To show voltage waveforms related to transmission-line reflections, the first plot shows output waveforms from the driver at the start of the cable (A/B); the second plot shows input waveforms to the receiver at the far end of the cable (Y).

8.2 Typical Application



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Figure 8-1. Differential Terminated Configuration With All Channels and Active Low Enable Used

8.2.1 Design Requirements

Resistor and capacitor (if used) termination values are shown for each laboratory experiment, but vary from system to system. For example, the termination resistor, R_T , must be within 20% of the characteristic impedance, Z_0 , of the cable and can vary from about 80Ω to 120Ω.

8.2.2 Detailed Design Procedure

Ensure values in [Absolute Maximum Ratings](#) are not exceeded.

Supply voltage, V_{IH} , and V_{IL} must comply with [Recommended Operating Conditions](#).

8.2.3 Application Curve

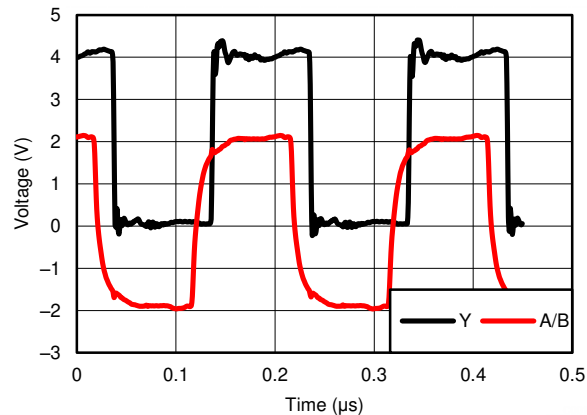


Figure 8-2. Differential 120Ω Terminated Output Waveforms (Cat 5E Cable)

8.3 Power Supply Recommendations

Place 0.1μF bypass capacitors close to the power-supply pins to reduce errors coupling in from noisy or high impedance power supplies.

8.4 Layout

8.4.1 Layout Guidelines

For best operational performance of the device, use good PCB layout practices, including:

- Noise can propagate into analog circuitry through the power pins of the circuit as a whole, as well as the operational amplifier. Bypass capacitors are used to reduce the coupled noise by providing low impedance power sources local to the analog circuitry.
 - Connect low-ESR, 0.1-μF ceramic bypass capacitors between each supply pin and ground, placed as close to the device as possible. A single bypass capacitor from $V+$ to ground is applicable for single-supply applications.
- Separate grounding for analog and digital portions of circuitry is one of the simplest and most effective methods of noise suppression. One or more layers on multilayer PCBs are usually devoted to ground planes. A ground plane helps distribute heat and reduces EMI noise pickup. Make sure to physically separate digital and analog grounds, paying attention to the flow of the ground current.
- To reduce parasitic coupling, run the input traces as far away from the supply or output traces as possible. If it is not possible to keep them separate, it is much better to cross the sensitive trace perpendicular as opposed to in parallel with the noisy trace.
- Place the external components as close to the device as possible. Keeping RF and RG close to the inverting input minimizes parasitic capacitance.
- Keep the length of input traces as short as possible. Always remember that the input traces are the most sensitive part of the circuit.
- Consider a driven, low-impedance guard ring around the critical traces. A guard ring can significantly reduce leakage currents from nearby traces that are at different potentials.

8.4.2 Layout Example

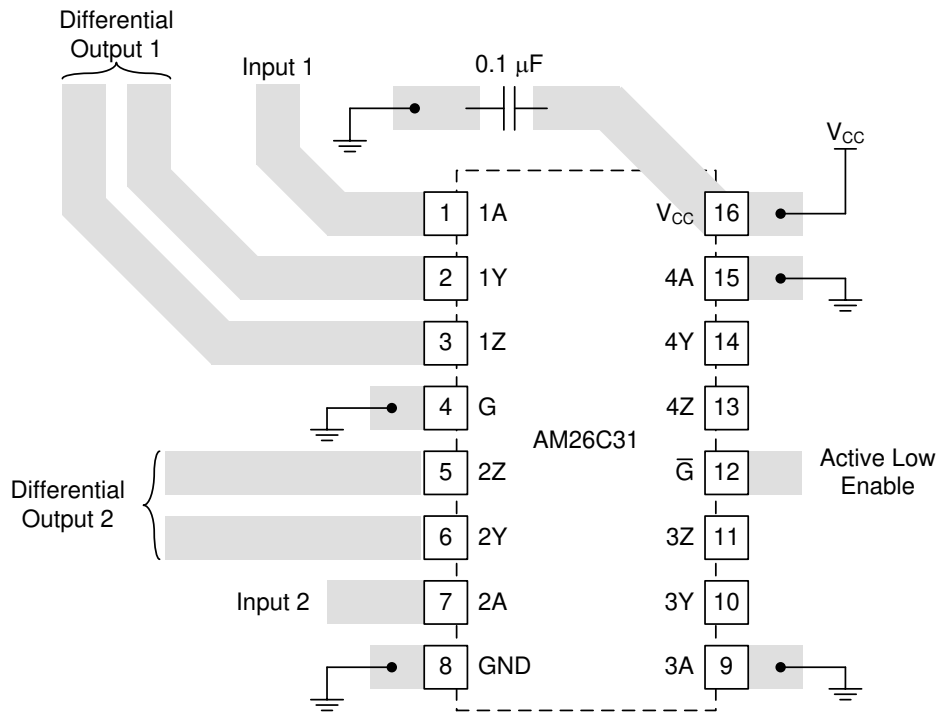


Figure 8-3. Trace Layout on PCB and Recommendations

9 Device and Documentation Support

9.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

9.2 Support Resources

TI E2E™ [support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

9.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.

All trademarks are the property of their respective owners.

9.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

9.5 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

10 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

| Changes from Revision O (June 2016) to Revision P (March 2024) | Page |
|---|-------------|
| • Changed the Device Information table to the <i>Package Information</i> table..... | 1 |
| • Changed <i>Thermal Information</i> table..... | 5 |
| • Changed Figure 5-1 | 7 |
| • Changed Figure 6-1 | 8 |

| Changes from Revision N (October 2011) to Revision O (February 2014) | Page |
|---|-------------|
| • Updated the <i>Features</i> section and added the <i>Applications</i> section, the <i>Device Information</i> table, <i>ESD Ratings</i> table, <i>Feature Description</i> section, <i>Device Functional Modes</i> , <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section..... | 1 |
| • Deleted <i>Ordering Information</i> table, see POA at the end of the data sheet..... | 1 |
| • Changed <i>Thermal Information</i> table..... | 5 |

| Changes from Revision M (June 2008) to Revision N (October 2011) | Page |
|---|-------------|
| • Changed units to mA from μ A to fix units typo..... | 4 |

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser based versions of this data sheet, refer to the left hand navigation.

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|------------------|--------------------------------------|----------------------|--------------|------------------------------------|-------------------------|
| 5962-9163901M2A | ACTIVE | LCCC | FK | 20 | 55 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-9163901M2A AM26C31M | Samples |
| 5962-9163901MEA | ACTIVE | CDIP | J | 16 | 25 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-9163901ME A AM26C31M | Samples |
| 5962-9163901MFA | ACTIVE | CFP | W | 16 | 25 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-9163901MF A AM26C31M | Samples |
| 5962-9163901Q2A | ACTIVE | LCCC | FK | 20 | 55 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-9163901Q2A AM26C31 MFKB | Samples |
| 5962-9163901QEA | ACTIVE | CDIP | J | 16 | 25 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-9163901QE A AM26C31MJB | Samples |
| 5962-9163901QFA | ACTIVE | CFP | W | 16 | 25 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-9163901QF A AM26C31MWB | Samples |
| AM26C31CD | OBSOLETE | SOIC | D | 16 | | TBD | Call TI | Call TI | 0 to 70 | AM26C31C | |
| AM26C31CDBR | OBSOLETE | SSOP | DB | 16 | | TBD | Call TI | Call TI | 0 to 70 | 26C31 | |
| AM26C31CN | ACTIVE | PDIP | N | 16 | 25 | RoHS & Green | NIPDAU | N / A for Pkg Type | 0 to 70 | AM26C31CN | Samples |
| AM26C31CNSR | ACTIVE | SO | NS | 16 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 26C31 | Samples |
| AM26C31ID | OBSOLETE | SOIC | D | 16 | | TBD | Call TI | Call TI | -40 to 85 | AM26C31I | |
| AM26C31IDBR | ACTIVE | SSOP | DB | 16 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | 26C31I | Samples |
| AM26C31IDBRE4 | ACTIVE | SSOP | DB | 16 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | 26C31I | Samples |
| AM26C31IDR | ACTIVE | SOIC | D | 16 | 2500 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | AM26C31I | Samples |
| AM26C31IDRG4 | OBSOLETE | SOIC | D | 16 | | TBD | Call TI | Call TI | -40 to 85 | AM26C31I | |
| AM26C31IN | ACTIVE | PDIP | N | 16 | 25 | RoHS & Green | NIPDAU | N / A for Pkg Type | -40 to 85 | AM26C31IN | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|---------------------|--------------------------------------|----------------------|--------------|------------------------------------|-------------------------|
| AM26C31INE4 | ACTIVE | PDIP | N | 16 | 25 | RoHS & Green | NIPDAU | N / A for Pkg Type | -40 to 85 | AM26C31IN | Samples |
| AM26C31INSR | ACTIVE | SO | NS | 16 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | 26C31I | Samples |
| AM26C31IPW | OBSOLETE | TSSOP | PW | 16 | | TBD | Call TI | Call TI | -40 to 85 | 26C31I | |
| AM26C31IPWR | ACTIVE | TSSOP | PW | 16 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | 26C31I | Samples |
| AM26C31IPWRG4 | OBSOLETE | TSSOP | PW | 16 | | TBD | Call TI | Call TI | -40 to 85 | 26C31I | |
| AM26C31MFKB | ACTIVE | LCCC | FK | 20 | 55 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-9163901Q2A AM26C31 MFKB | Samples |
| AM26C31MJB | ACTIVE | CDIP | J | 16 | 25 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-9163901QE A AM26C31MJB | Samples |
| AM26C31MWB | ACTIVE | CFP | W | 16 | 25 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-9163901QF A AM26C31MWB | Samples |
| AM26C31QD | OBSOLETE | SOIC | D | 16 | | TBD | Call TI | Call TI | -40 to 125 | AM26C31Q | |
| AM26C31QDG4 | OBSOLETE | SOIC | D | 16 | | TBD | Call TI | Call TI | -40 to 125 | 26C31Q | |
| AM26C31QDR | ACTIVE | SOIC | D | 16 | 2500 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | AM26C31Q | Samples |
| AM26C31QDRG4 | ACTIVE | SOIC | D | 16 | 2500 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | 26C31Q | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF AM26C31, AM26C31M :

- Catalog : [AM26C31](#)

- Enhanced Product : [AM26C31-EP](#), [AM26C31-EP](#)

- Military : [AM26C31M](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

- Enhanced Product - Supports Defense, Aerospace and Medical Applications

- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| AM26C31CDBR | SSOP | DB | 16 | 2000 | 330.0 | 16.4 | 8.35 | 6.6 | 2.4 | 12.0 | 16.0 | Q1 |
| AM26C31CDR | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |
| AM26C31CNSR | SO | NS | 16 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |
| AM26C31IDBR | SSOP | DB | 16 | 2000 | 330.0 | 16.4 | 8.35 | 6.6 | 2.4 | 12.0 | 16.0 | Q1 |
| AM26C31IDR | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |
| AM26C31IDRG4 | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |
| AM26C31INSR | SO | NS | 16 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |
| AM26C31IPWR | TSSOP | PW | 16 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| AM26C31IPWRG4 | TSSOP | PW | 16 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| AM26C31QDR | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |
| AM26C31QDRG4 | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---------------|--------------|-----------------|------|------|-------------|------------|-------------|
| AM26C31CDBR | SSOP | DB | 16 | 2000 | 356.0 | 356.0 | 35.0 |
| AM26C31CDR | SOIC | D | 16 | 2500 | 340.5 | 336.1 | 32.0 |
| AM26C31CNSR | SO | NS | 16 | 2000 | 356.0 | 356.0 | 35.0 |
| AM26C31IDBR | SSOP | DB | 16 | 2000 | 356.0 | 356.0 | 35.0 |
| AM26C31IDR | SOIC | D | 16 | 2500 | 340.5 | 336.1 | 32.0 |
| AM26C31IDRG4 | SOIC | D | 16 | 2500 | 340.5 | 336.1 | 32.0 |
| AM26C31INSR | SO | NS | 16 | 2000 | 356.0 | 356.0 | 35.0 |
| AM26C31IPWR | TSSOP | PW | 16 | 2000 | 367.0 | 367.0 | 35.0 |
| AM26C31IPWRG4 | TSSOP | PW | 16 | 2000 | 367.0 | 367.0 | 35.0 |
| AM26C31QDR | SOIC | D | 16 | 2500 | 350.0 | 350.0 | 43.0 |
| AM26C31QDRG4 | SOIC | D | 16 | 2500 | 340.5 | 336.1 | 32.0 |

TUBE


*All dimensions are nominal

| Device | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | T (μm) | B (mm) |
|-----------------|--------------|--------------|------|-----|--------|--------|--------|--------|
| 5962-9163901M2A | FK | LCCC | 20 | 55 | 506.98 | 12.06 | 2030 | NA |
| 5962-9163901MFA | W | CFP | 16 | 25 | 506.98 | 26.16 | 6220 | NA |
| 5962-9163901Q2A | FK | LCCC | 20 | 55 | 506.98 | 12.06 | 2030 | NA |
| 5962-9163901QFA | W | CFP | 16 | 25 | 506.98 | 26.16 | 6220 | NA |
| AM26C31CD | D | SOIC | 16 | 40 | 507 | 8 | 3940 | 4.32 |
| AM26C31CDE4 | D | SOIC | 16 | 40 | 507 | 8 | 3940 | 4.32 |
| AM26C31CDG4 | D | SOIC | 16 | 40 | 507 | 8 | 3940 | 4.32 |
| AM26C31CN | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| AM26C31ID | D | SOIC | 16 | 40 | 507 | 8 | 3940 | 4.32 |
| AM26C31IDE4 | D | SOIC | 16 | 40 | 507 | 8 | 3940 | 4.32 |
| AM26C31IDG4 | D | SOIC | 16 | 40 | 507 | 8 | 3940 | 4.32 |
| AM26C31IN | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| AM26C31INE4 | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| AM26C31IPW | PW | TSSOP | 16 | 90 | 530 | 10.2 | 3600 | 3.5 |
| AM26C31MFKB | FK | LCCC | 20 | 55 | 506.98 | 12.06 | 2030 | NA |
| AM26C31MWB | W | CFP | 16 | 25 | 506.98 | 26.16 | 6220 | NA |
| AM26C31QD | D | SOIC | 16 | 40 | 505.46 | 6.76 | 3810 | 4 |
| AM26C31QDG4 | D | SOIC | 16 | 40 | 505.46 | 6.76 | 3810 | 4 |



PACKAGE OUTLINE

NS0016A

SOP - 2.00 mm max height

SOP



4220735/A 12/2021

NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.

EXAMPLE BOARD LAYOUT

NS0016A

SOP - 2.00 mm max height

SOP



4220735/A 12/2021

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

NS0016A

SOP - 2.00 mm max height

SOP



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:7X

4220735/A 12/2021

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4040047-6/M 06/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 -  D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.



4220204/A 02/2017

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220204/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

DB0016A



PACKAGE OUTLINE

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



4220763/A 05/2022

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-150.

EXAMPLE BOARD LAYOUT

DB0016A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220763/A 05/2022

NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0016A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220763/A 05/2022

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP2-F16

GENERIC PACKAGE VIEW

FK 20

LCCC - 2.03 mm max height

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



4229370VA\

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



| DIM \ PINS ** | 14 | 16 | 18 | 20 |
|---------------|------------------------|------------------------|------------------------|------------------------|
| A | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC |
| B MAX | 0.785 (19,94) | .840 (21,34) | 0.960 (24,38) | 1.060 (26,92) |
| B MIN | — | — | — | — |
| C MAX | 0.300 (7,62) | 0.300 (7,62) | 0.310 (7,87) | 0.300 (7,62) |
| C MIN | 0.245 (6,22) | 0.245 (6,22) | 0.220 (5,59) | 0.245 (6,22) |



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

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